



#510  
9/19/02

PATENT  
Customer No. 22,852  
Attorney Docket No. 04329.2567

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: )  
)  
Yasuhiro YAMAJI ) Group Art Unit: 2827  
)  
Application No.: 09/871,671 ) Examiner: J. Mitchell  
)  
Filed: June 4, 2001 )  
)  
For: SEMICONDUCTOR DEVICE )  
USING SUBSTRATE HAVING )  
CUBIC STRUCTURE AND )  
METHOD OF MANUFACTURING )  
THE SAME )

*Smith*  
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Commissioner for Patents  
Washington, DC 20231

Sir:

AMENDMENT

In reply to the Office Action dated June 19, 2002, please amend the application as follows:

IN THE CLAIMS:

Please cancel claim 24 without prejudice or disclaimer of the subject matter thereof, amend claims 1-10, 12-23, and 26, and rewrite claim 25, as follows:

1. (Amended) A semiconductor device, comprising:  
a cylindrical substrate having wirings formed thereon; and  
at least one semiconductor chip mounted on a circumferential surface of said substrate, said semiconductor chip being bent along the surface of said substrate and having bumps in contact with the wirings.

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